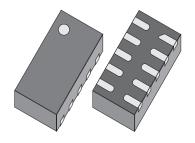
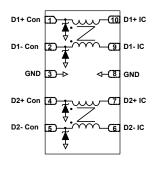


# Common mode filter with ESD protection for high speed serial interface



QFN-10L 2.6 x 1.35 x 0.5



#### **Product status link**

ECMF04-4HSM10

| Product summary |  |  |  |  |
|-----------------|--|--|--|--|
| 10              |  |  |  |  |
|                 |  |  |  |  |

#### **Features**

- Very large differential bandwidth to comply with HDMI Full HD, MIPI, USB2.0, USB3.2 Gen 1, Display Port and other high speed serial interfaces
- Provides -20 dB attenuation at 700 MHz in LTE bands
- High common mode attenuation:- 25 dB between 800 MHz 900 MHz
- · Low PCB space consumption
- Thin package for compact applications: 0.55 mm max.
- · High reduction of parasitic elements through integration
- · RoHS package

#### Complies with the following standards

- IEC 61000-4-2, level 4:
  - ±15 kV (air discharge)
  - ±8 kV (contact discharge)

### **Applications**

- · Mobile phones
- · Notebook, laptop
- · Portable devices
- PND

### **Description**

The ECMF04-4HSM10 is a highly integrated common mode filter designed to suppress EMI/RFI common mode noise on high speed differential serial buses like HDMI Full HD, MIPI, Display Port and other high speed serial interfaces.

The device has a very large differential bandwidth to comply with these standards and can protect and filter two differential lanes.



## 1 Characteristics

Table 1. Absolute maximum ratings (T<sub>amb</sub> = 25 °C)

| Symbol           | Parameter                          | Value             | Unit |    |
|------------------|------------------------------------|-------------------|------|----|
|                  |                                    | IEC 61000-4-2:    |      |    |
| V <sub>PP</sub>  | Peak pulse voltage                 | Contact discharge | 8    | kV |
|                  |                                    | Air discharge     | 16   |    |
| I <sub>RMS</sub> | Maximum RMS current                | 100               | mA   |    |
| T <sub>op</sub>  | Operating ambient temperature rang | -55 to +125       |      |    |
| T <sub>j</sub>   | Maximum junction temperature       | 125               | °C   |    |
| T <sub>stg</sub> | Storage temperature range          | -55 to +150       |      |    |

Figure 1. Electrical characteristics (definitions)

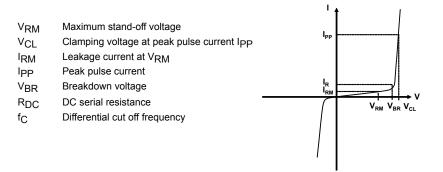


Table 2. Electrical characteristics (T<sub>amb</sub> = 25 °C)

| Symbol          | Test conditions                | Min. | Тур. | Max. | Unit |
|-----------------|--------------------------------|------|------|------|------|
| V <sub>BR</sub> | I <sub>R</sub> = 1 mA          | 6    |      |      | V    |
| I <sub>RM</sub> | V <sub>RM</sub> = 3 V per line |      |      | 100  | nA   |
| R <sub>DC</sub> | DC serial resistance           |      | 5    |      | Ω    |

**Table 3. Pin description** 

| Pin number | Description      | Description |           |
|------------|------------------|-------------|-----------|
| 1          | D1+ to connector | 6           | D2- to IC |
| 2          | D1- to connector | 7           | D2+ to IC |
| 3          | GND              | 8           | GND       |
| 4          | D2+ to connector | 9           | D1- to IC |
| 5          | D2- to connector | 10          | D1+ to IC |

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### 1.1 Characteristics (curves)

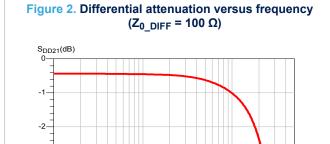


Figure 3. Common mode attenuation versus frequency  $(Z_{0\_COM} = 50 \ \Omega)$ 

Figure 4. ESD response to IEC61000-4-2 (+8 kV contact discharge)

f(Hz)

1E8

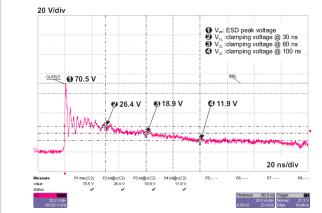


Figure 5. ESD response to IEC61000-4-2 (-8 kV contact discharge)

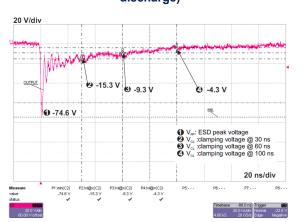


Figure 6. HDMI1.4 3.35 Gbps eye diagram without ECMF04-4HSM10

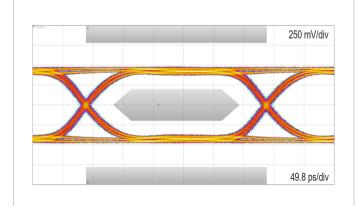
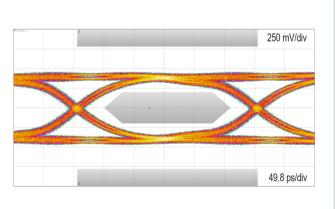


Figure 7. HDMI1.4 3.35 Gbps eye diagram with ECMF04-4HSM10



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Figure 8. USB2.0 480 Mbps eye diagram without device

200 mV/div

347.2 ps/div

Figure 9. USB2.0 480 Mbps eye diagram with device

200 mV/div

347.2 ps/div

Figure 10. USB3.2 Gen 1 5.0 Gbps eye diagram without ECMF04-4HSM10 (with worst cable and equalizer)

100 mV/div

33.3 ps/div

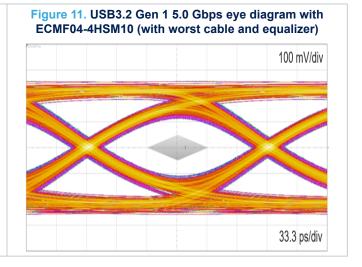
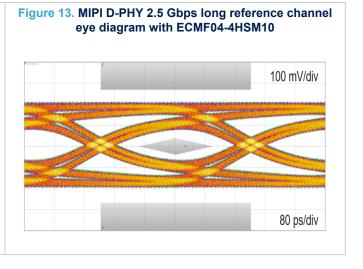


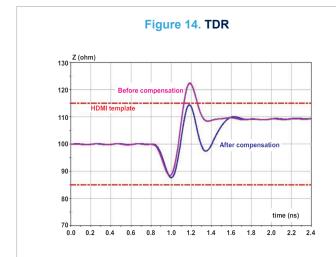
Figure 12. MIPI D-PHY 2.5 Gbps long reference channel eye diagram without ECMF04-4HSM10

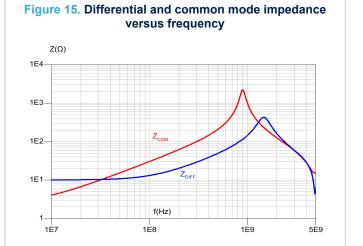
100 mV/div
80 ps/div



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# 2 Application information

Figure 16. HDMI schematic

More application information available in following AN:

- AN4356: "Antenna desense on handheld equipment"
- AN4511: "Common mode filters"
- AN4540: "MHL link filtering and protection"

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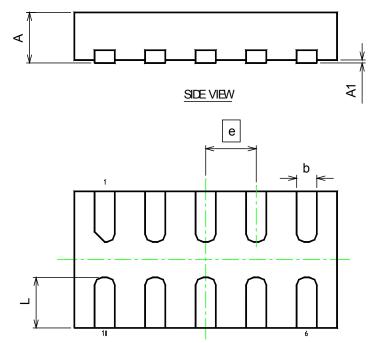
# 3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Figure 17. QFN10L package outline

## 3.1 QFN-10L package information

TOP VIEW



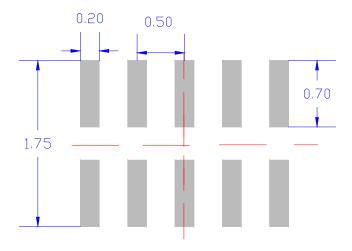
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Table 4. QFN10L package mechanical data

|      | Dimensions  |      |      |  |
|------|-------------|------|------|--|
| Ref. | Millimeters |      |      |  |
|      | Min.        | Тур. | Max. |  |
| A    | 0.45        | 0.50 | 0.55 |  |
| A1   | 0.00        | 0.02 | 0.05 |  |
| b    | 0.15        | 0.20 | 0.25 |  |
| D    | 2.55        | 2.60 | 2.65 |  |
| E    | E 1.30      |      | 1.40 |  |
| е    |             | 0.50 |      |  |
| L    | L 0.40      |      | 0.60 |  |

Figure 18. Footprint recommendations (mm)



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# 4 PCB assembly recommendation

Figure 19. Recommended PCB layout

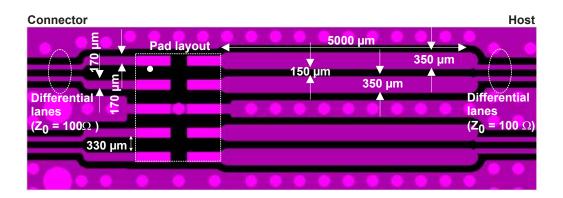
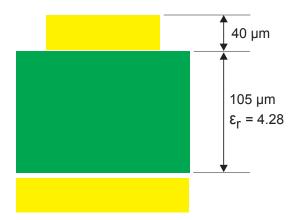


Figure 20. PCB stack dimensions



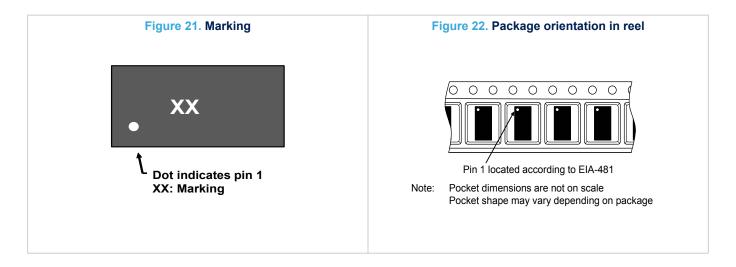
## 4.1 Solder paste

- 1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
- 2. "No clean" solder paste is recommended.
- 3. Offers a high tack force to resist component movement during high speed.
- 4. Use solder paste with fine particles: powder particle size is 20-38 μm.

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## 4.2 QFN-10L packing information



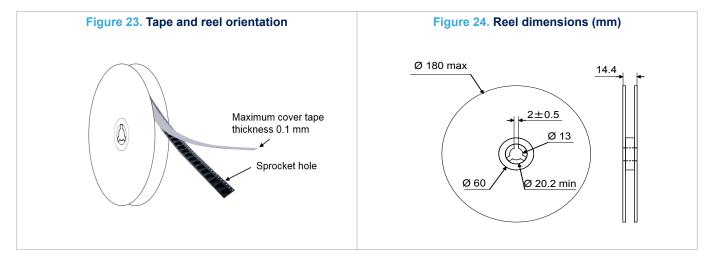
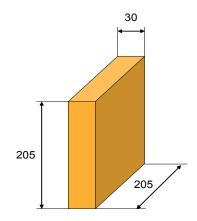


Figure 25. Inner box dimensions (mm)



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Dolt identifying Pin A1 location

2.0

4.0

0.20

0.65

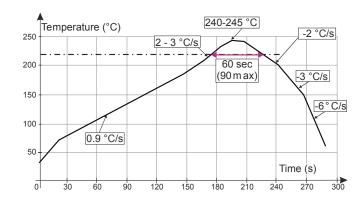
Figure 26. Tape and reel outline

All dimensions are typical values in mm

User direction of unreeling

### 4.3 Solder reflow

Figure 27. ST ECOPACK® recommended soldering reflow profile for PCB mounting



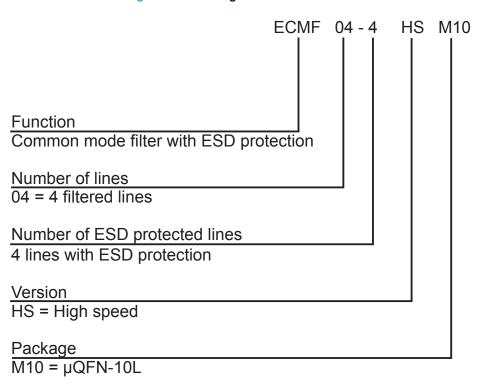
Note: Minimize air convection currents in the reflow oven to avoid component movement. Maximum soldering profile corresponds to the latest IPC/JEDEC J-STD-020.

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# 5 Ordering information

Figure 28. Ordering information scheme



| Order code    | Marking           | Package  | Weight | Base qty. | Delivery mode |
|---------------|-------------------|----------|--------|-----------|---------------|
| ECMF04-4HSM10 | KK <sup>(1)</sup> | μQFN-10L | 5 mg   | 3000      | Tape and reel |

<sup>1.</sup> The marking can be rotated by 90° to differentiate assembly location

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# **Revision history**

Table 5. Document revision history

| Date          | Version | Changes  |
|---------------|---------|--|
| 03-Oct-2013   | 1       | Initial release.   |
| 25-Aug-2014   | 2       | Added Figure 5: Differential (ZDD21) and common mode (ZCC21) impedance versus frequency.                 |
| 13-Dec-2017 3 |         | Updated Table 1.   |
|               |         | Updated Figure 6, Figure 7, Figure 8, Figure 9, Figure 10 and Figure 11.  Added Figure 12 and Figure 13. |

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P6KE8.2A SA110CA SA60CA SA64CA SMBJ12CATR SMBJ8.0A SMLJ30CA-TP ESD101-B1-02ELS E6327 ESD112-B1-02EL E6327
ESD119B1W01005E6327XTSA1 ESD5V0J4-TP ESD5V0L1B02VH6327XTSA1 ESD7451N2T5G 19180-510 CPDT-5V0USP-HF
3.0SMCJ33CA-F 3.0SMCJ36A-F HSPC16701B02TP D3V3Q1B2DLP3-7 D55V0M1B2WS-7 DESD5V0U1BL-7B DRTR5V0U4SL-7
SCM1293A-04SO ESD200-B1-CSP0201 E6327 ESD203-B1-02EL E6327 SM12-7 SMF8.0A-TP SMLJ45CA-TP CEN955 W/DATA
82350120560 82356240030 VESD12A1A-HD1-GS08 CPDUR5V0R-HF CPDUR24V-HF CPDQC5V0U-HF CPDQC5V0USP-HF
CPDQC5V0-HF D1213A-01LP4-7B D1213A-02WL-7 ESDLIN1524BJ-HQ 5KP100A